

ELECTRONIC ASSEMBLIES WITH HIGH CAPACITY HEAT SINKS

Abstract of the Disclosure

5 An electronic assembly comprising one or more high performance integrated
circuits includes at least one high capacity heat sink. The heat sink, which
comprises a number of fins projecting substantially radially from a core, is
structured to capture air from a fan and to direct the air to optimize heat transfer
from the heat sink. The heat sink fins can be formed in different shapes. In one
10 embodiment, the fins are curved. In another embodiment, the fins are bent. In yet
another embodiment, the fins are curved and bent. Methods of fabricating heat
sinks and electronic assemblies, as well as application of the heat sink to an
electronic assembly and to an electronic system, are also described.

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